Unit: mm

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type ($L^2-\pi$ -MOS V)

2SK4018

Chopper Regulator, DC-DC Converter and Motor Drive Applications

4-V gate drive

• Low drain-source ON-resistance: R_{DS} (ON) = 0.28 Ω (typ.)

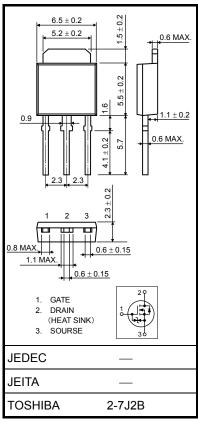
• High forward transfer admittance: |Y_{fs}| = 3.5 S (typ.)

• Low leakage current: I_{DSS} = 100 μA (max) (V_{DS} = 100 V)

• Enhancement mode: $V_{th} = 0.8$ to 2.0 V ($V_{DS} = 10$ V, $I_D = 1$ mA)

Absolute Maximum Ratings (Ta = 25°C)

Character	istic	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	100	V
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	100	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC (Note 1)	I _D	3	Α
	Pulse (Note 1)	I _{DP}	12	Α
Drain power dissipatio	n (Tc = 25°C)	P_{D}	20	W
Single-pulse avalanch	e energy (Note 2)	E _{AS}	140	mJ
Avalanche current		I _{AR}	3	Α
Repetitive avalanche	energy (Note 3)	E _{AR}	2	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature r	ange	T _{stg}	-55 to 150	°C



Weight: 0.36 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristic	Symbol	Мах	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	6.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	125	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 25 mH, R_G = 25 Ω , I_{AR} = 3 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



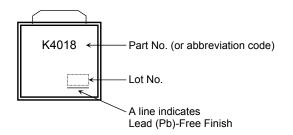
Electrical Characteristics (Ta = 25°C)

Charac	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μА
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V	_	_	100	μА
Drain-source br voltage	eakdown	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	100	_	_	٧
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON-resistance		Pro (out)	V _{GS} = 4 V, I _D = 2 A	_	0.36	0.45	Ω
		R _{DS} (ON)	V _{GS} = 10 V, I _D = 2 A	_	0.28	0.35	
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2 A	1.5	3.5	_	S
Input capacitano	e	C _{iss}		_	280	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	50	_	pF
Output capacitance		Coss		_	105	_	
Switching time	Rise time	t _r	V _{GS} _{0V} I _D = 2A _{OC} V _{OUT} R _L = ₂₅ Ω	_	20	_	
	Turn-on time	t _{on}		_	50	_	no
	Fall time	t _f		_	40	_	ns
	Turn-off time	t _{off}	$V_{DD} \approx 50V$ Duty $\leq 1\%$, $t_{W} = 10 \mu s$	_	170	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	13.5	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 80 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		8.5	_	nC
Gate-drain ("Miller") charge		Q _{gd}		_	5	_	

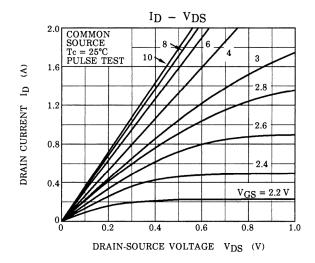
Source-Drain Ratings and Characteristics (Ta = 25°C)

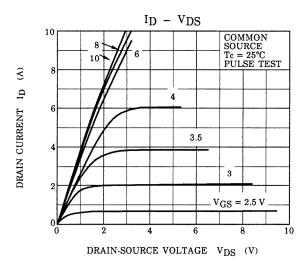
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	3	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	12	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 3 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	$I_{DR} = 3 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 50 \text{ A} / \mu \text{s}$	_	100	_	ns
Reverse recovery charge	Q _{rr}		_	0.2	_	μС

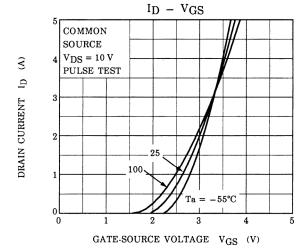
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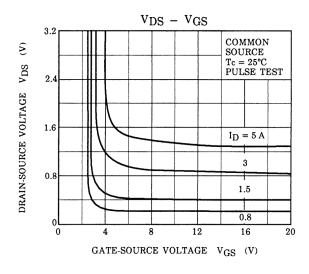


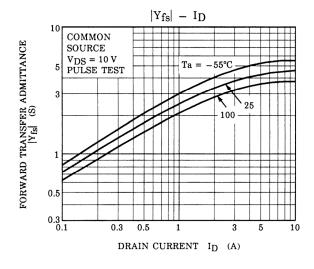
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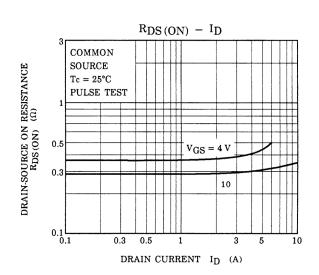




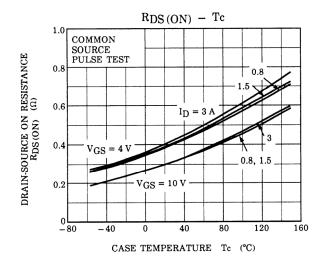


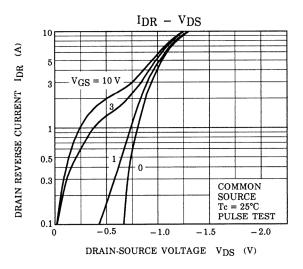


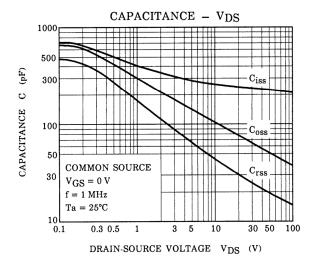


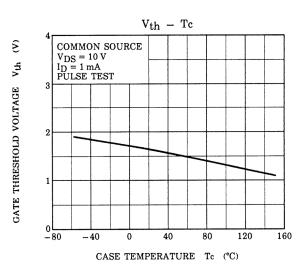


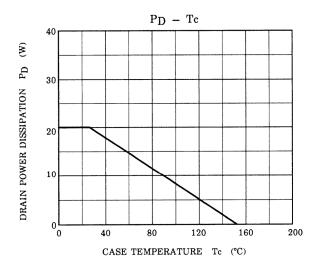
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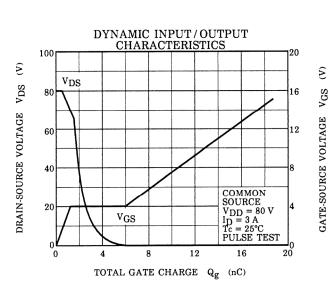




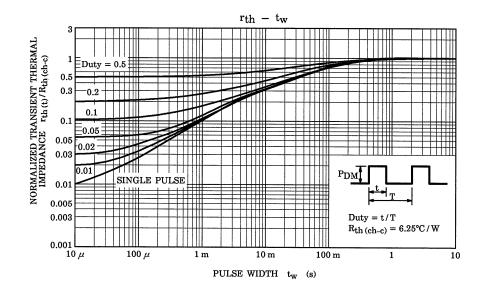


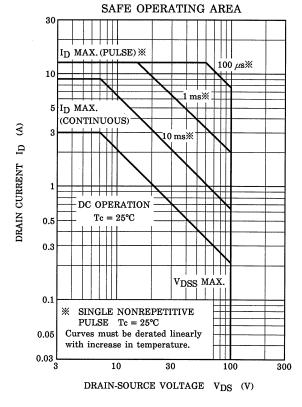


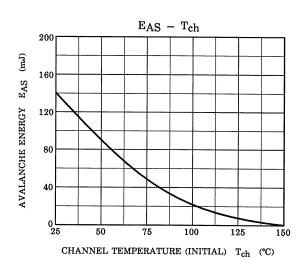


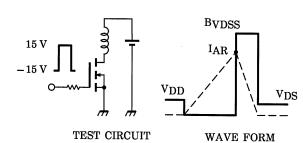


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$$\begin{split} &\mathrm{RG} = 25~\Omega\\ &\mathrm{V_{DD}} = 25~\mathrm{V,~L} = 25~\mathrm{mH} \end{split}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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RESTRICTIONS ON PRODUCT USE

20070701-EN GENERAL

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